Abstracts

Effect of Package Shape on Spurious Coupling Among Microstrip Discontinuities

H. Cebi and K.C. Gupta. "Effect of Package Shape on Spurious Coupling Among Microstrip Discontinuities." 1996 MTT-S International Microwave Symposium Digest 96.3 (1996 Vol. III [MWSYM]): 1823-1826.

Effects of a metallic package on the performance of a microstrip circuit are attributed mainly to the modifications of spurious couplings among various discontinuities. This paper describes a method for computing the effect of the package shape on the interactions among discontinuities. It is shown that chamfering of the corners of a rectangular package can reduce the spurious coupling between two microstrip open-end stubs.

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